# 100 V, 2.0 A, Low V<sub>CE(sat)</sub> **PNP Transistor**

ON Semiconductor's e<sup>2</sup>PowerEdge family of low V<sub>CE(sat)</sub> transistors are miniature surface mount devices featuring ultra low saturation voltage (V<sub>CE(sat)</sub>) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC-DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e<sup>2</sup>PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

#### **Features**

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

# MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-140	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-7.0	Vdc
Base Current - Continuous	I <sub>B</sub>	1.0	Α
Collector Current - Continuous	Ic	2.0	Α
Collector Current - Peak	I <sub>CM</sub>	3.0	Α

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 1)	800 6.5	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 1)	155	°C/W
Total Device Dissipation  T <sub>A</sub> = 25°C  Derate above 25°C	P <sub>D</sub> (Note 2)	2.0 15.6	W mW/°C
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub> (Note 2)	64	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

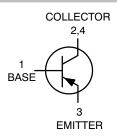
- FR-4 @ 7.6 mm<sup>2</sup>, 1 oz. copper traces.
   FR-4 @ 645 mm<sup>2</sup>, 1 oz. copper traces.



## ON Semiconductor®

http://onsemi.com

# -100 VOLTS, 2.0 AMPS PNP LOW V<sub>CE(sat)</sub> TRANSISTOR



### **MARKING DIAGRAM**



SOT-223 **CASE 318E** STYLE 1



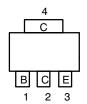
= Assembly Location

= Year

= Work Week

= Specific Device Code = Pb-Free Package

# **PIN ASSIGNMENT**



Top View Pinout

# **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
NSS1C200MZ4T1G NSV1C200MZ4T1G	SOT-223 (Pb-Free)	1000/ Tape & Reel	
NSS1C200MZ4T3G	SOT-223 (Pb-Free)	4000/ Tape & Reel	

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS				-	:
Collector – Emitter Breakdown Voltage (I <sub>C</sub> = -10 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)CEO</sub>	-100			Vdc
Collector – Base Breakdown Voltage (I <sub>C</sub> = -0.1 mAdc, I <sub>E</sub> = 0)	V <sub>(BR)CBO</sub>	-140			Vdc
Emitter – Base Breakdown Voltage (I <sub>E</sub> = -0.1 mAdc, I <sub>C</sub> = 0)	V <sub>(BR)EBO</sub>	-7.0			Vdc
Collector Cutoff Current (V <sub>CB</sub> = -140 Vdc, I <sub>E</sub> = 0)	I <sub>CBO</sub>			-100	nAdc
Emitter Cutoff Current (V <sub>EB</sub> = -6.0 Vdc)	I <sub>EBO</sub>			-50	nAdc
ON CHARACTERISTICS	<u> </u>		•	•	
DC Current Gain (Note 3) $ (I_C = -10 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $	h <sub>FE</sub>	150 120 80 50		360	
Collector – Emitter Saturation Voltage (Note 3) $ (I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A}) $ $ (I_C = -0.5 \text{ A, } I_B = -0.050 \text{ A}) $ $ (I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A}) $ $ (I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A}) $	VCE(sat)			-0.040 -0.080 -0.125 -0.220	٧
Base – Emitter Saturation Voltage (Note 3) $(I_C = -1.0 \text{ A}, I_B = -0.100 \text{ A})$	V <sub>BE(sat)</sub>			-0.950	V
Base – Emitter Turn–on Voltage (Note 3) (I <sub>C</sub> = -1.0 A, V <sub>CE</sub> = -2.0 V)	V <sub>BE(on)</sub>			-0.850	V
Cutoff Frequency ( $I_C = -100 \text{ mA}$ , $V_{CE} = -5.0 \text{ V}$ , $f = 100 \text{ MHz}$ )	f <sub>T</sub>		120		MHz
Input Capacitance (V <sub>EB</sub> = 3.0 V, f = 1.0 MHz)	Cibo		200		pF
Output Capacitance (V <sub>CB</sub> = 10 V, f = 1.0 MHz)	Cobo		22		pF

<sup>3.</sup> Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

# **TYPICAL CHARACTERISTICS**

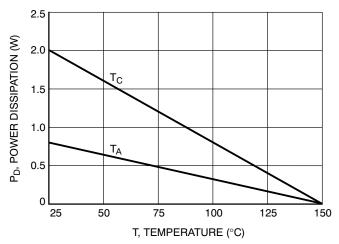


Figure 1. Power Derating

## **TYPICAL CHARACTERISTICS**

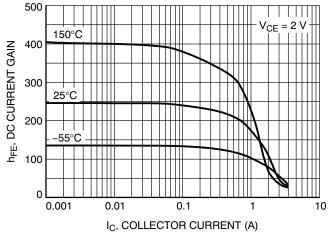
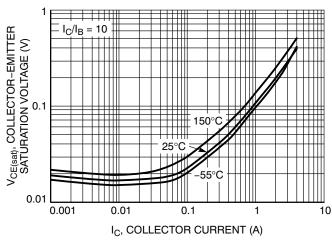


Figure 2. DC Current Gain

Figure 3. DC Current Gain



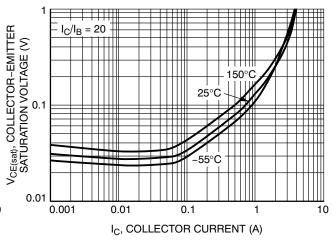
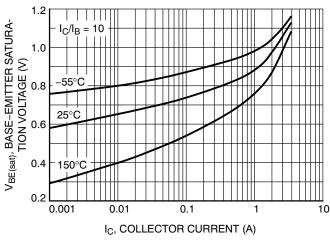


Figure 4. Collector-Emitter Saturation Voltage

Figure 5. Collector-Emitter Saturation Voltage



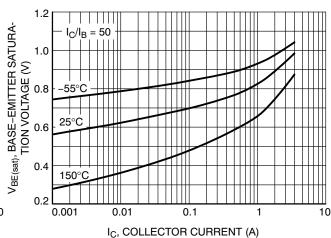
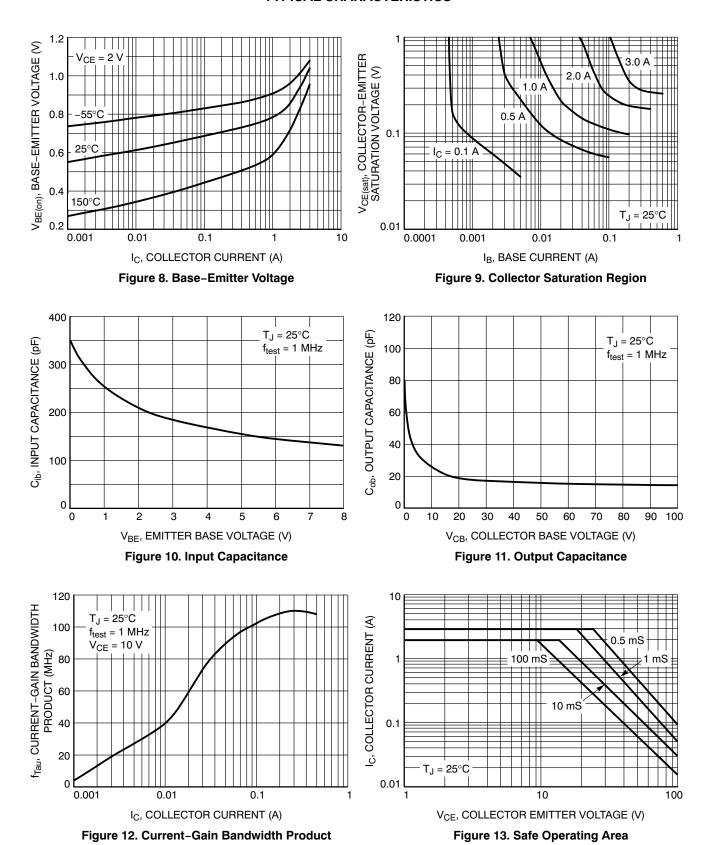


Figure 6. Base-Emitter Saturation Voltage

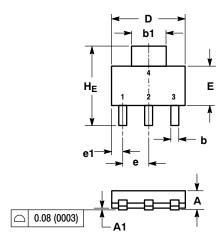
Figure 7. Base-Emitter Saturation Voltage

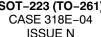
#### **TYPICAL CHARACTERISTICS**



#### PACKAGE DIMENSIONS

# SOT-223 (TO-261) CASE 318E-04





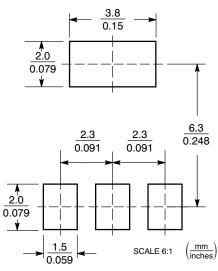
- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20		_	0.008		_
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°		10°	0°	_	10°

STYLE 1: PIN 1. BASE

- 2. COLLECTOR 3. EMITTER
- 4. COLLECTOR

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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